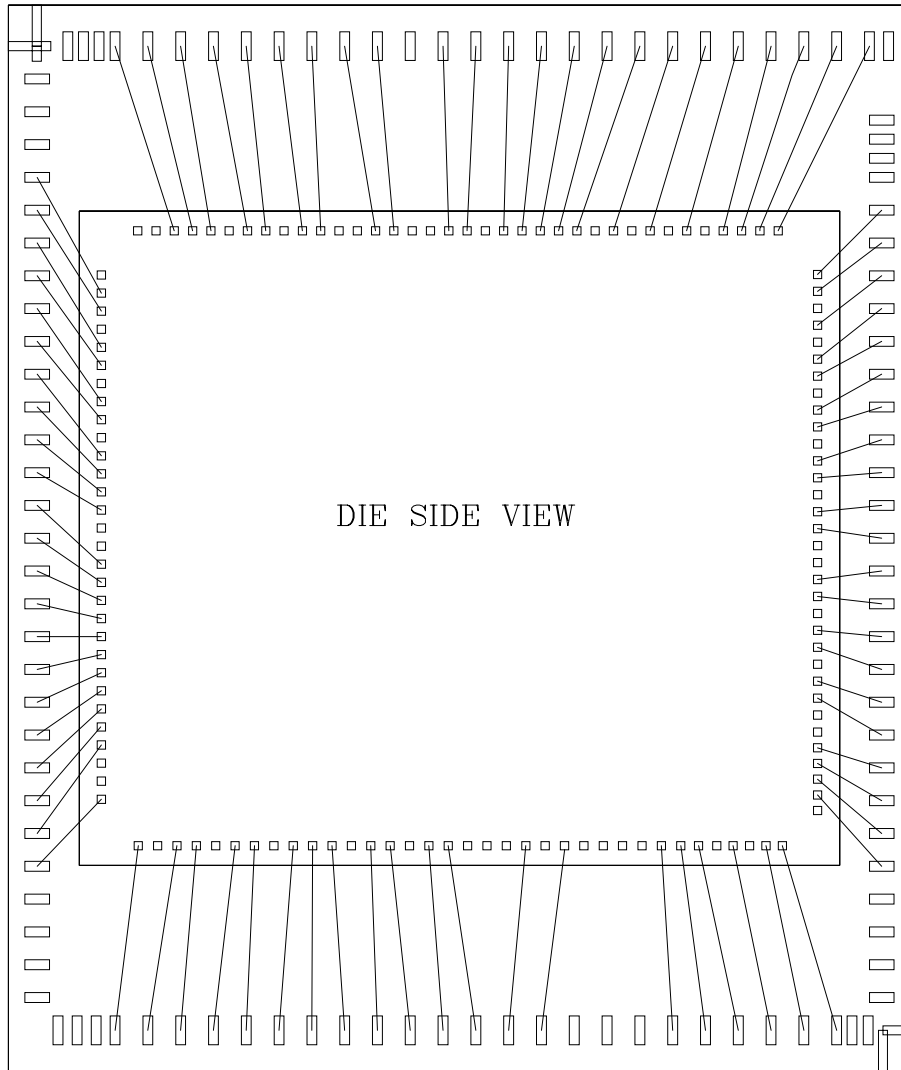


**Signetics Korea**

TITLE:

11X13MM 100 FBGA
2 LAYER
0.80MM PITCH
BONDING DIAGRAM

NOTE:

A1 — A10
TOP
VIEW
K1 — K10

SUB-TITLE:		CUSTOMER: UPenn	DIE PAD SIZE:			
FILE NAME: BLB-11131(rev1)		DEVICE: DTMROC2000	DIE SIZE (X/Y): 9.274X7.978			
FRAME DWG#: EEV-FLB11131(rev1)		CUSTOMER BD#:	BOND PAD OPEN SIZE/PITCH:			
DETAIL DWG#: EEV-FLB11131(rev1)		SIG. BD#:	WIRE DIAMETER: 1.0MIL			
FRAME STOCK#:		PART #:	LONGEST WIRE LENGTH: 31MIL			
SCALE: N/S	SHEET: 1 OF 1	FRAME CODE:	SHORTEST WIRE LENGTH: 99MIL			
DATE	REV.	DESCRIPTION		DRAWN	CHECKED	APPROVED
09/25/01	-	1ST DRAFT		MJ BAIK	DS SEO	